

**PURCHASE ORDER ATTACHMENT TQA-28 (00)****SOLDERABILITY  
REV. G (20 Jan 1982)****I. General**

Leads, terminals or surface areas of item(s) called out on this Purchase Order which require soldering by Raytheon must meet the solderability requirements specified below.

**II. Sampling**

Where the solderability requirements are called out on the print/specification, the specification requirement given shall be used. When sample callouts are not otherwise stated on the print/specification, sampling shall be per MIL-STD-105D, level 1, single sample, normal inspection, 2.5 AQL.

**III. Requirements**

Where the solderability requirements are called out on the print/specification, the specification requirements shall be used. When solderability requirements are not called out on the print/specification all leads, terminals or surface areas shall conform, as a minimum, to the requirements of notes 1.0, 2.0, or 3.0 below, as applicable. Seller shall maintain records traceable to each shipment that all solderability test requirements have been complied with.

- 1.0 Components/Materials, other than those specified in Note 2.0 or 3.0 below shall meet the methods and acceptance requirements of MIL-STD-202, Method 208 or MIL-STD-750, Method 2062 (as applicable) with particular attention to Paragraph 4.0 of MIL-STD-202, Method 208 and the following conditions:
- 1.1 Electrical rejects from the same manufactured lot which exhibit acceptable lead characteristics may be used for solderability test.
  - 1.2 Components/materials which are restricted from mechanical dipping due to weight, dimensions or shape, may be hand dipped using the same immersion, dwell and emersion times as noted in Paragraphs 4.5 of MIL-STD-202, Method 208.
- 2.0 Microelectronics shall meet the methods and acceptance requirements of MIL-STD-883, Method 2003, with particular attention to Paragraph 3.0 and the following condition:
- 2.1 Electrical rejects from the same manufactured lot which exhibit acceptable lead characteristics may be used for solderability test.
- 3.0 Hand Soldering (Soldering Iron) Connections. Solderability of terminals, lugs, or leads which must be hand soldered due to weight, dimension or shape shall meet the methods and acceptance requirements of MIL-STD-202, Method 208 with particular attention to Paragraph 4.0 and the following conditions:
- 3.1 Electrical rejects from the same manufactured lot which exhibit acceptable lead characteristics may be used for solderability test.
  - 3.2 If solid solder is used, flux may be applied by brush rather than dip.
  - 3.3 The soldering iron used shall not produce a magnetic field or inject electrical energy detrimental to the item being solder tested.